

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)							
PCN #: A-0602-04R1 DATE:	21-Jun-2006	MEANS C	F DISTIN	IGUISHING C	HANGED DEVICES:		
Product Affected: Products built in 655L 24.5x1 FCBGA. Refer to the attached the affected part numbers. Date Effective: 14-Jun-2006		☐ Produc ☐ Back M ☐ Date C ☐ Other	I ark	Lot # will	have "B" prefix		
Contact: Geoffrey Cortes							
Title: Product Quality Assurance		Attachmen	t:	Yes	☐ No		
Phone #: (408) 284-8321							
Fax #: (408) 284-1450		Samples:	Please co	ntact your loca	l sales representative for		
E-mail: Geoffrey.Cortes@idt.com			sample re	equest & availa	bility.		
DESCRIPTION AND PURPOSE OF CHANGE:							
 □ Die Technology □ Wafer Fabrication Process □ Assembly Process □ Equipment □ Material □ Testing ■ Manufacturing Site □ Data Sheet 	This notification is to amend solder ball composition that was inadvertently written as 95.5Sn/4Ag/0.5Cu in PCN# A-0602-04, published in 16-Mar-2006. The correct solder ball composition is 96.5Sn/3Ag/0.5Cu. There is no change in the PCN affectivity date.						
П	There is no	change in	me PCN	arrectivity dat	ie.		
Other							
RELIABILITY/QUALIFICATION SUMMARY: There is no expected change to the product quality or reliability performance.							
CUSTOMER ACKNOWLEDGMENT OF RECEIPT: IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable. IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.							
Customer:		Appro	oval for s	shipments pr	rior to effective date.		
Name/Date:	E-N	Mail Addres	ss:				
Title:	Pho	one# /Fax#	: <u> </u>				
CUSTOMER COMMENTS:							
IDT ACKNOWLEDGMENT OF RECEIPT:							
RECD. BY:		DATE:					

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PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN #: A-0602-04R1

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT has qualified STATSChipPAC in Korea as an alternate assembly facility for 655L, 24.5x19.5mm FCBGA package using the assembly material set as listed in the Table 1.

There is no change in the moisture sensitive level (MSL) as a result of this change.

Attachment I outlines the qualification data and the affected part # list.

A revised PCN is being issued to correct the solder ball composition. Please refer to Table 1 for details.

Table 1

Description	Existing	Add		
Assembly Location	Amkor, Philippines and Korea	STATSChipPAC, Korea		
Assembly Material	95Pb/5Sn (High Pb bump), NAU6 (Underfill), 96.5Sn/3Ag/0.5Cu (Solder Ball)	95Pb/5Sn (High Pb bump), CRP-4152RA (Underfill), 96.5Sn/3Ag/0.5Cu (Solder Ball)		

Sample Availability:

Samples are already available for customer evaluation.

Please contact your local IDT sales representative for your sample request and availability.



PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT I - PCN # : A-0602-04R1

Qualification Information and Qualification Tests Result:

Test Vehicles: 1681L, 42.5mm FCBGA (3 assembly lots)

Test Description	Test Method	Sample Size /# of Fails	Test Results (SS/Rej)
* Temperature Cycling (Cond B, 1000 cycles)	JESD22-A104-B	45/0	45/0
* HAST (130°C/85% RH, unbiased, 100 hours)	JESD22-A102-C	45/0	45/0
** High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103-C	77/0	77/0

Notes:

** One assembly lot

* Test requires moisture pre-conditioning sequence per JESD22-A113C.

IDTAMB0480A5RH IDTAMB0480A5RJ

Affected Part #s